

FIG. 1
(CONVENTIONAL ART)

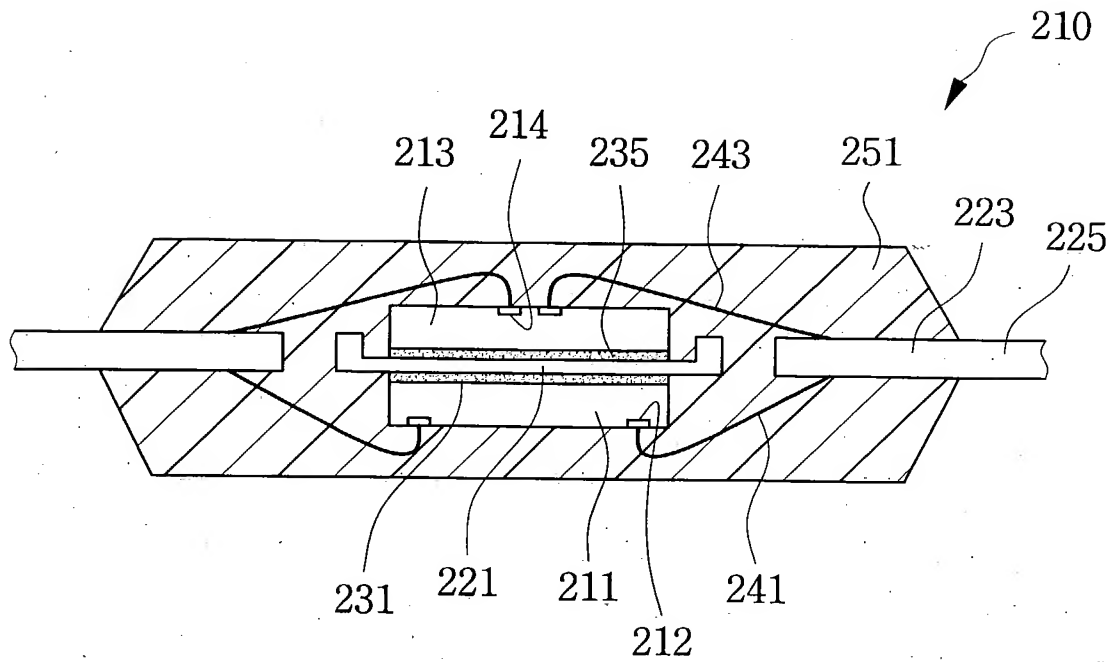


FIG. 2

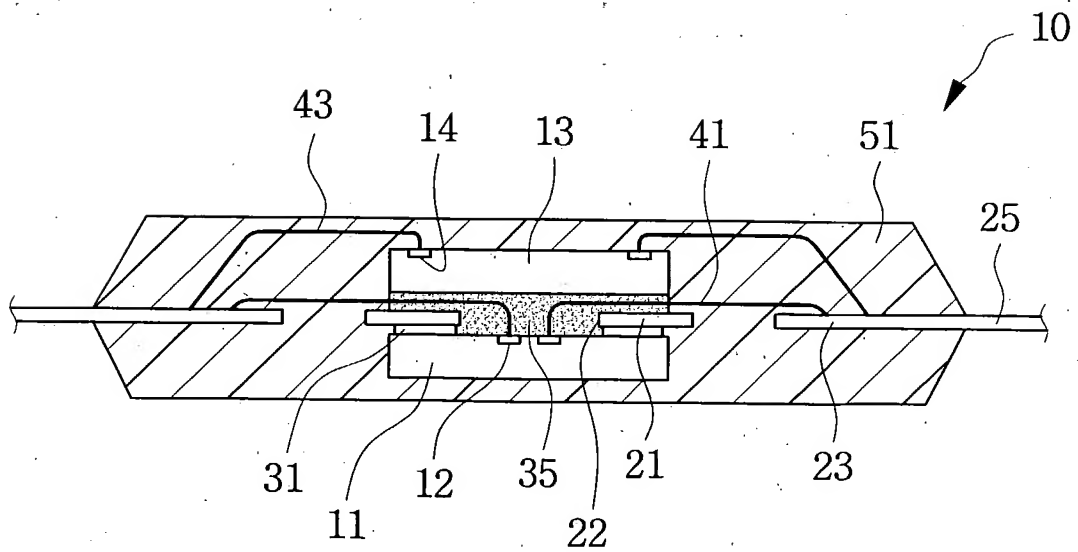


FIG. 3

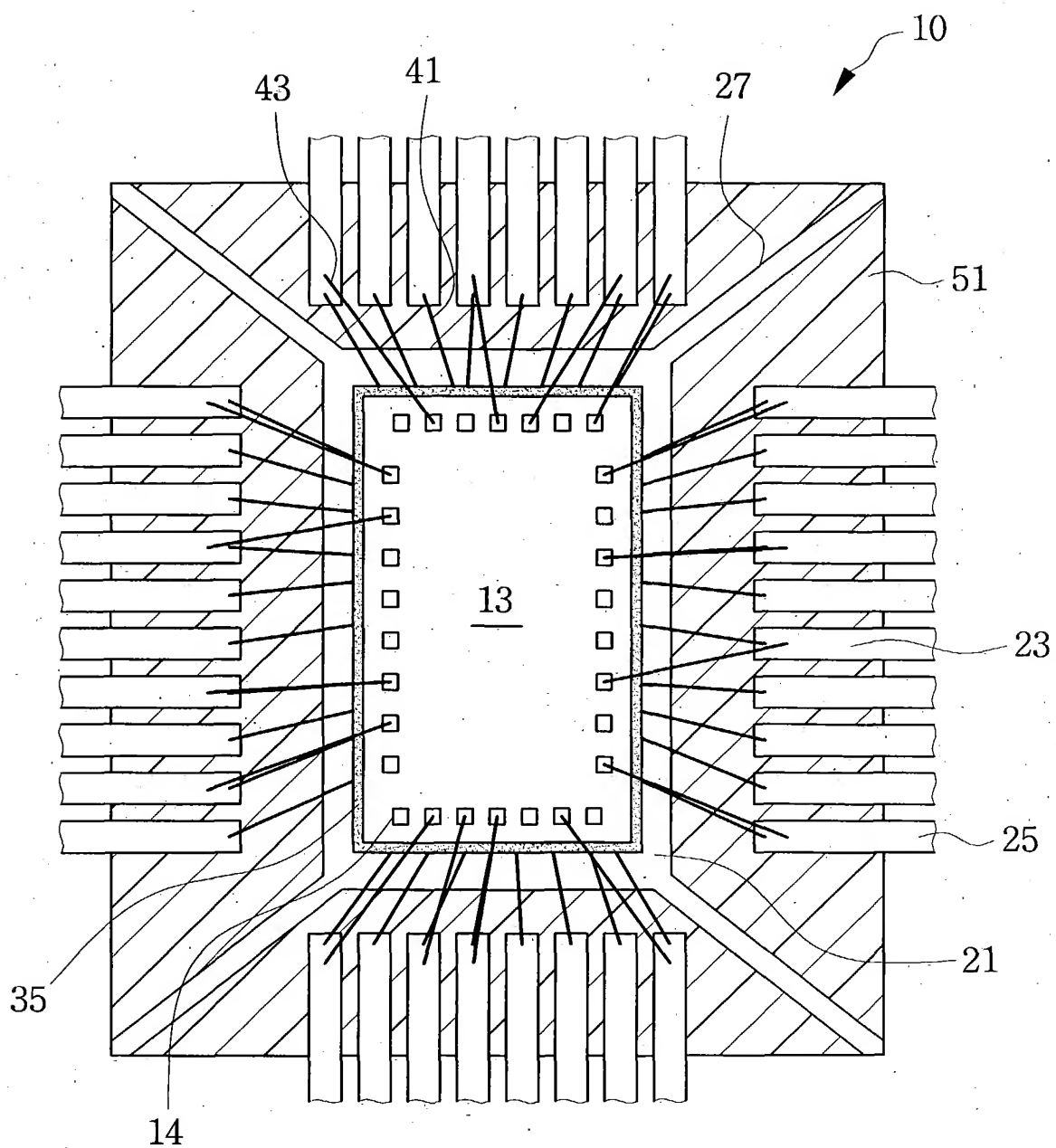


FIG. 4a

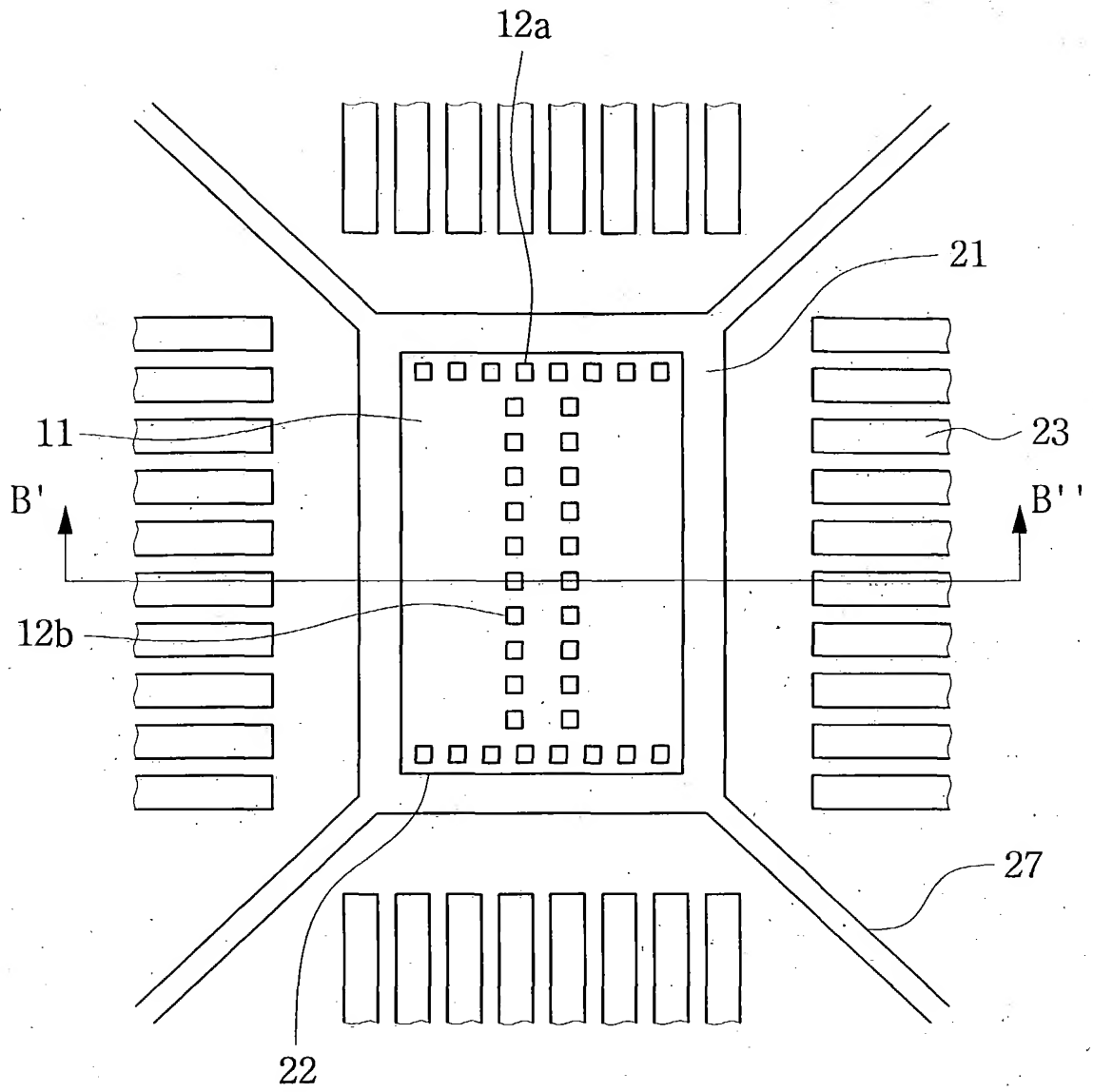


FIG 4b

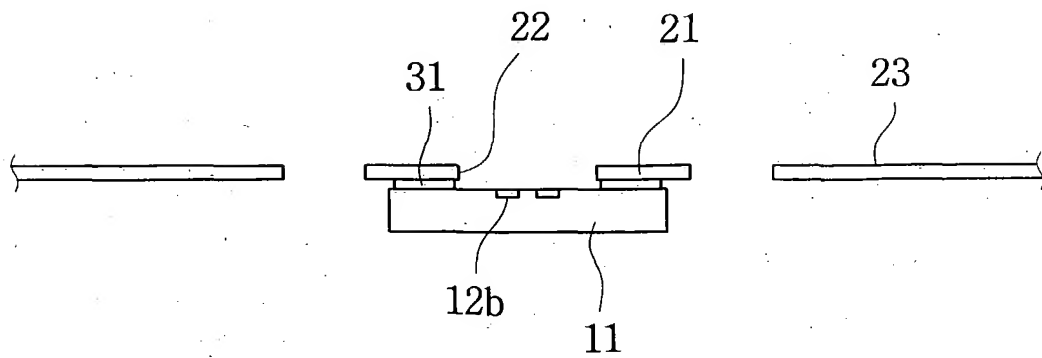


FIG. 5a

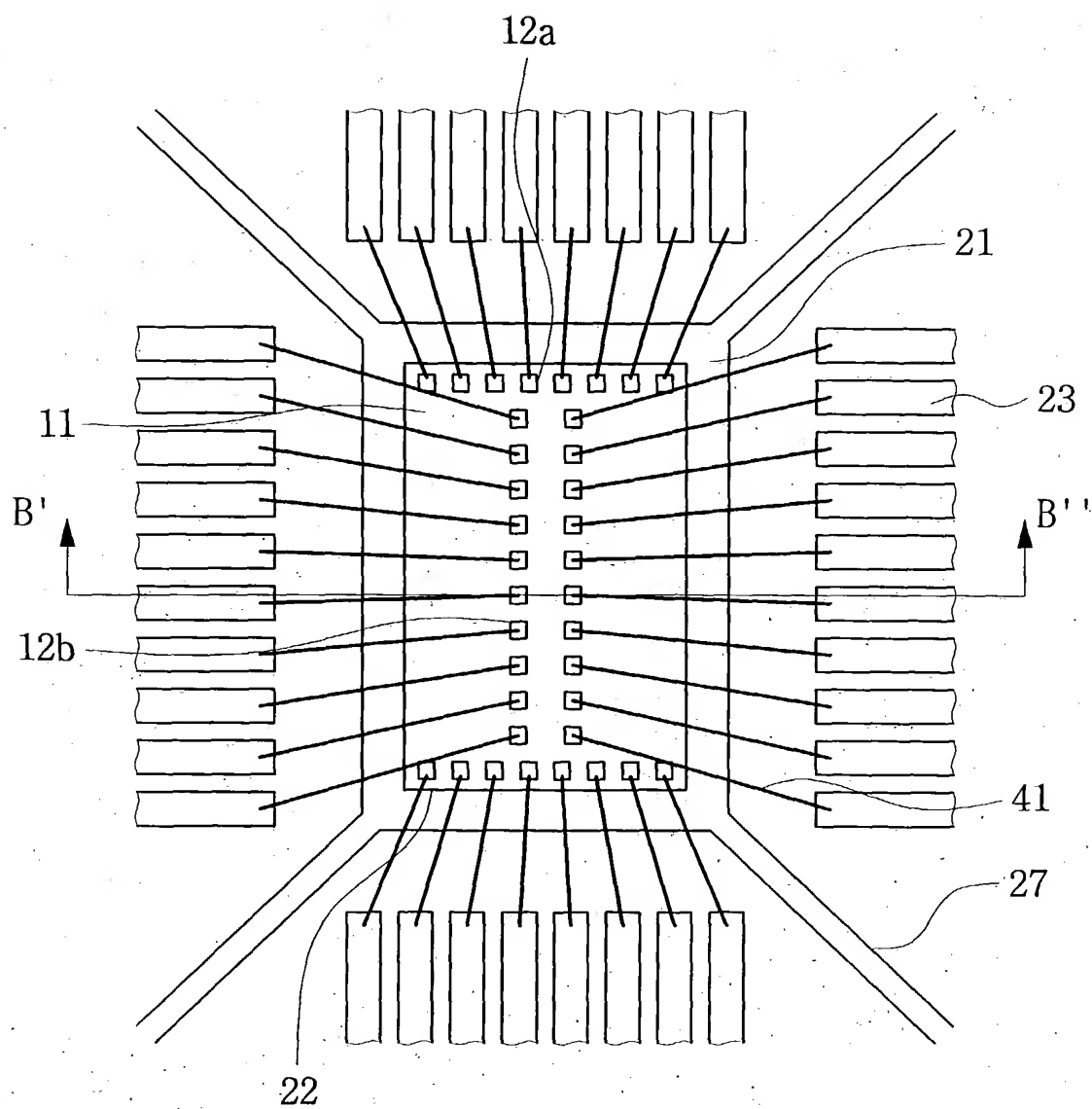


FIG. 5b

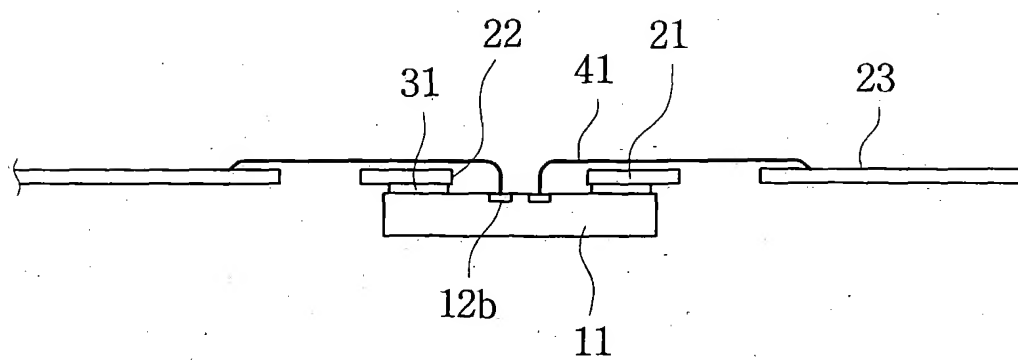


FIG. 6a

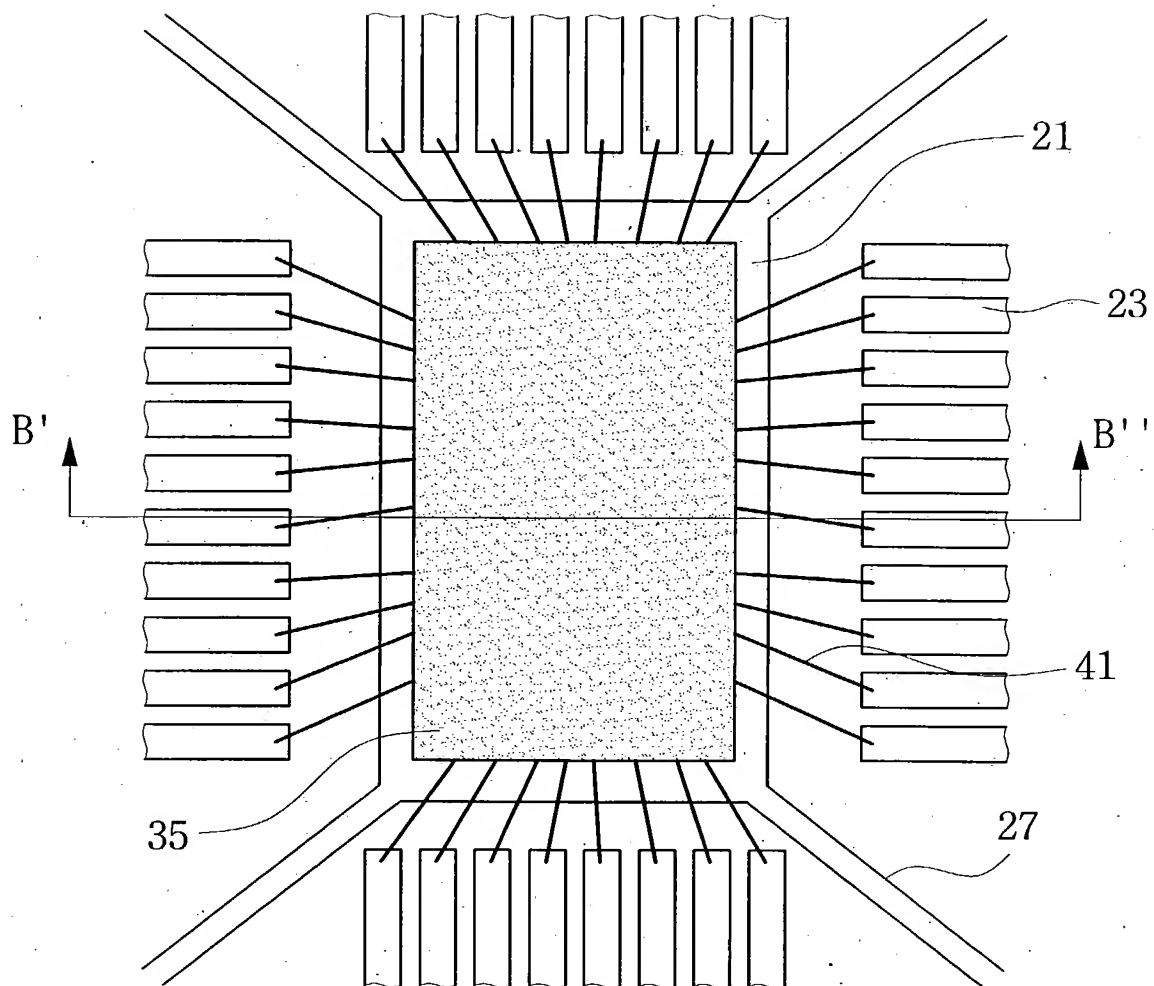
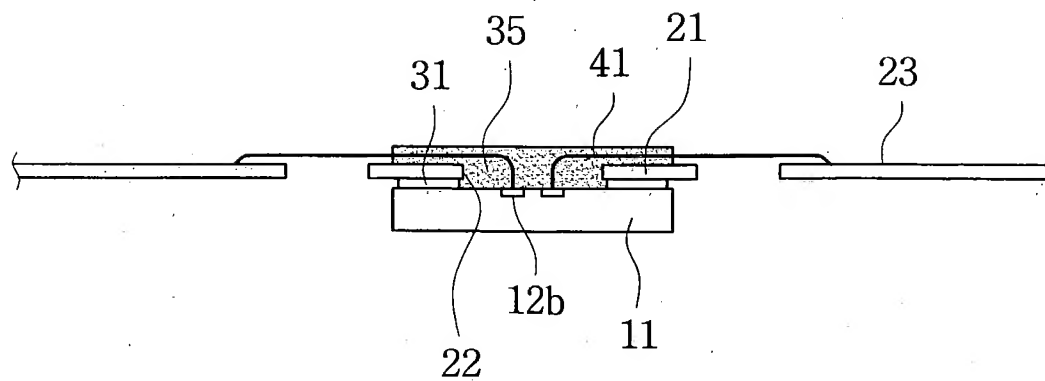


FIG. 6b



Top view of a semiconductor device 100. A central chip 13 is shown with a grid of contacts. The chip is surrounded by a frame 14. Various external components are connected to the chip, including a set of contacts 21 at the top, a set of contacts 23 on the right, a set of contacts 27 at the bottom, and a set of contacts 35 on the left. A set of contacts 41 is also shown on the right side. Arrows B' and B'' indicate magnetic field directions.

A cross-sectional view of a semiconductor device. A central core (13) is shown with a top layer (31) and a bottom layer (35). The core is flanked by side contacts (21) and (22). A central contact (14) is positioned between the side contacts. The device is mounted on a substrate (11) with a central opening (12b). A top contact (41) is located on the top surface of the core. A bottom contact (23) is located on the bottom surface of the core. The device is surrounded by a protective layer (20).

FIG. 8a

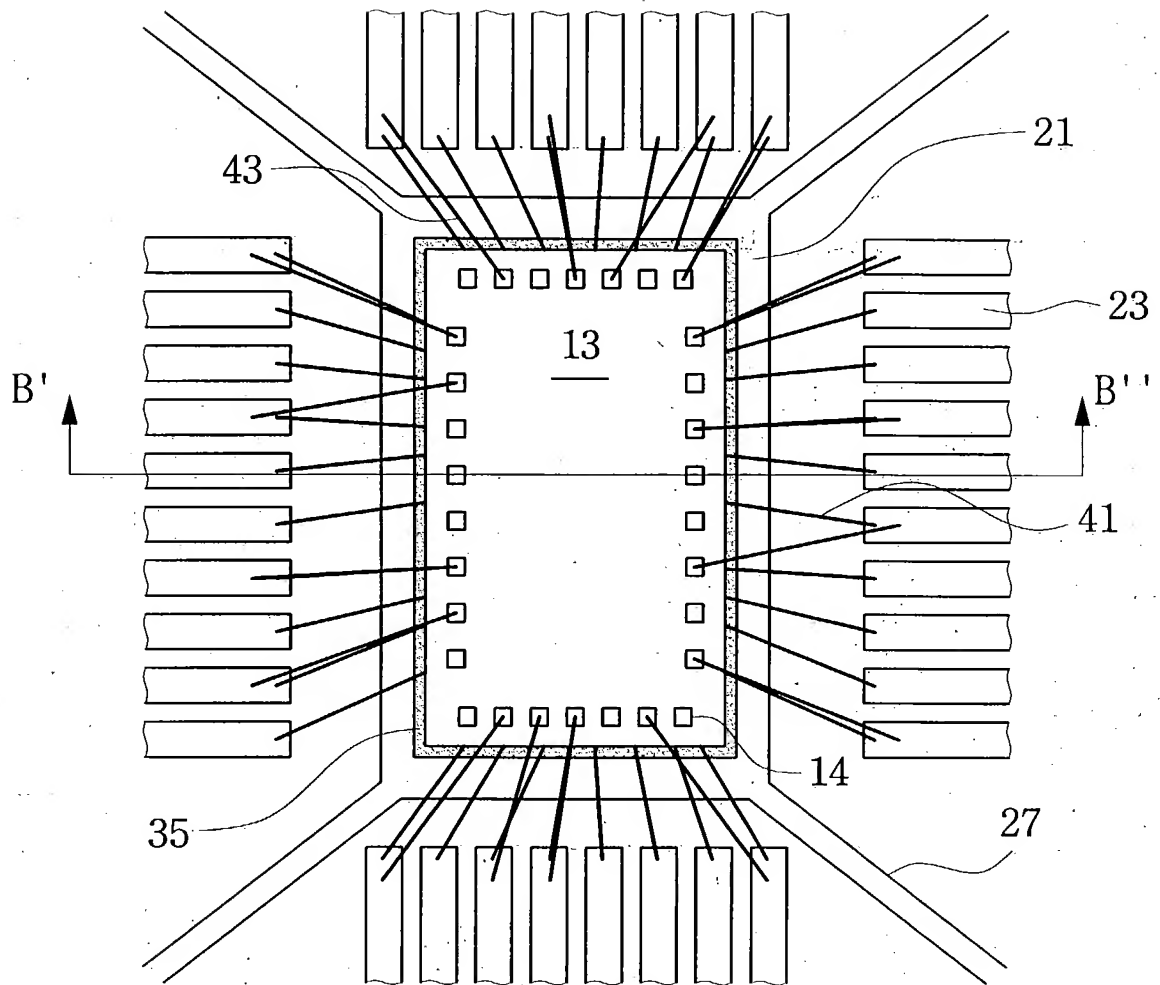


FIG. 8b

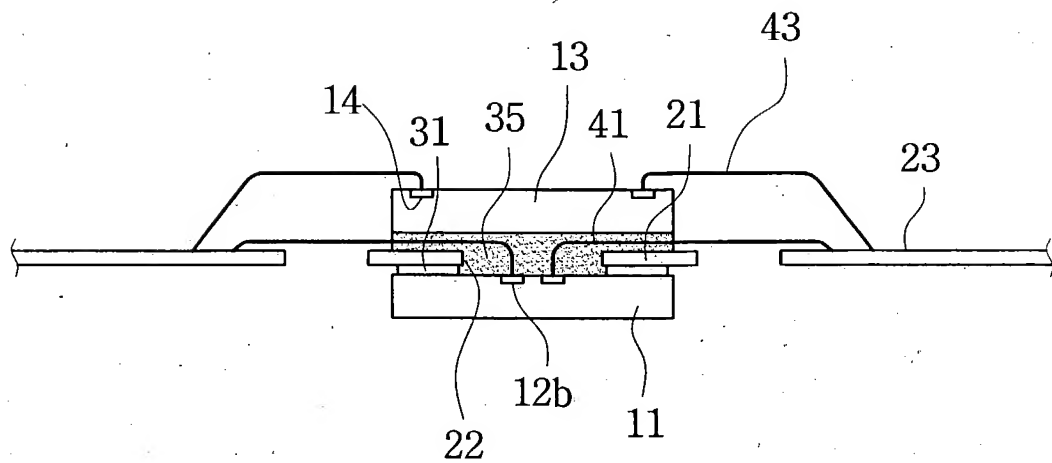


FIG. 9

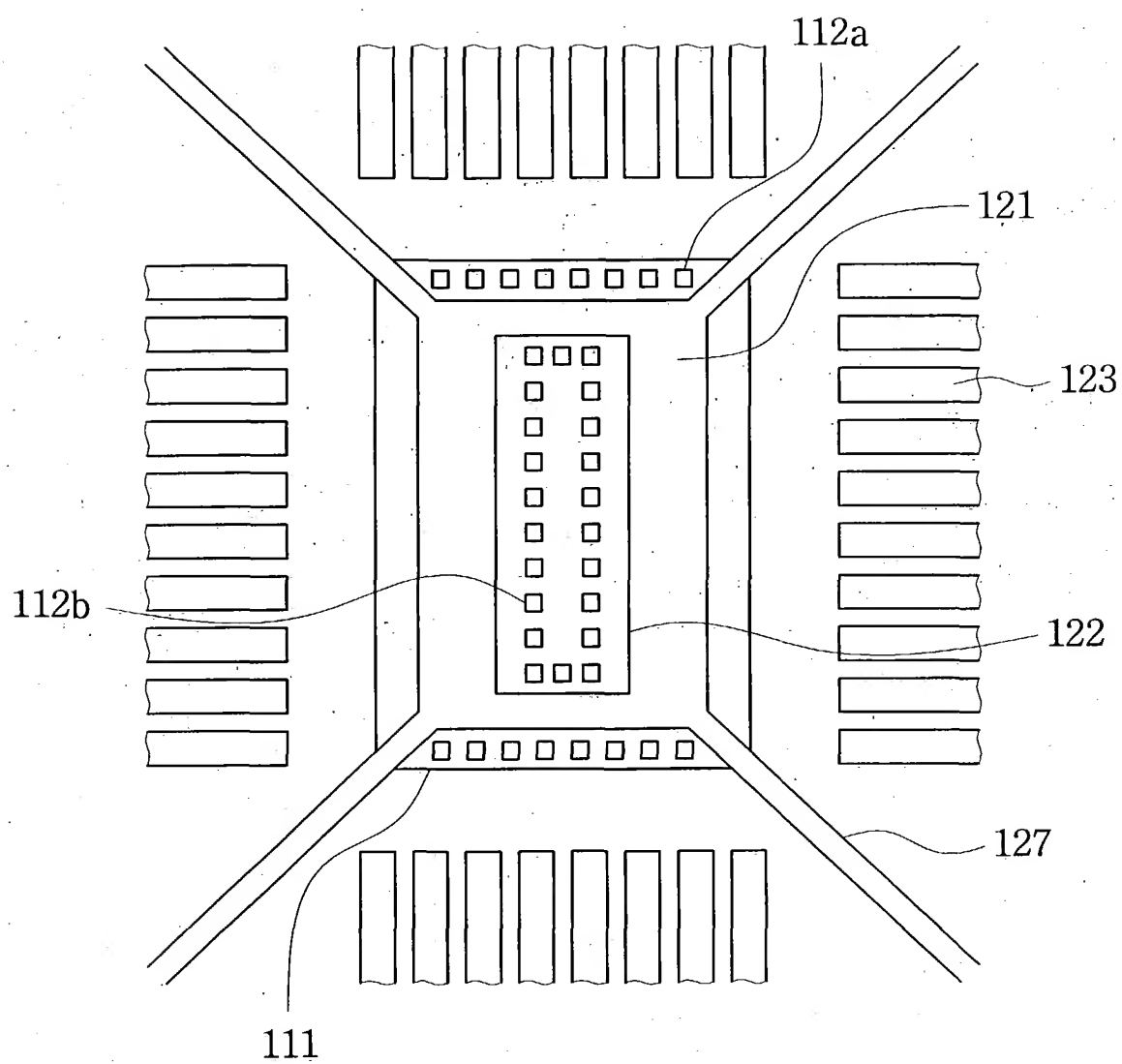


FIG. 10

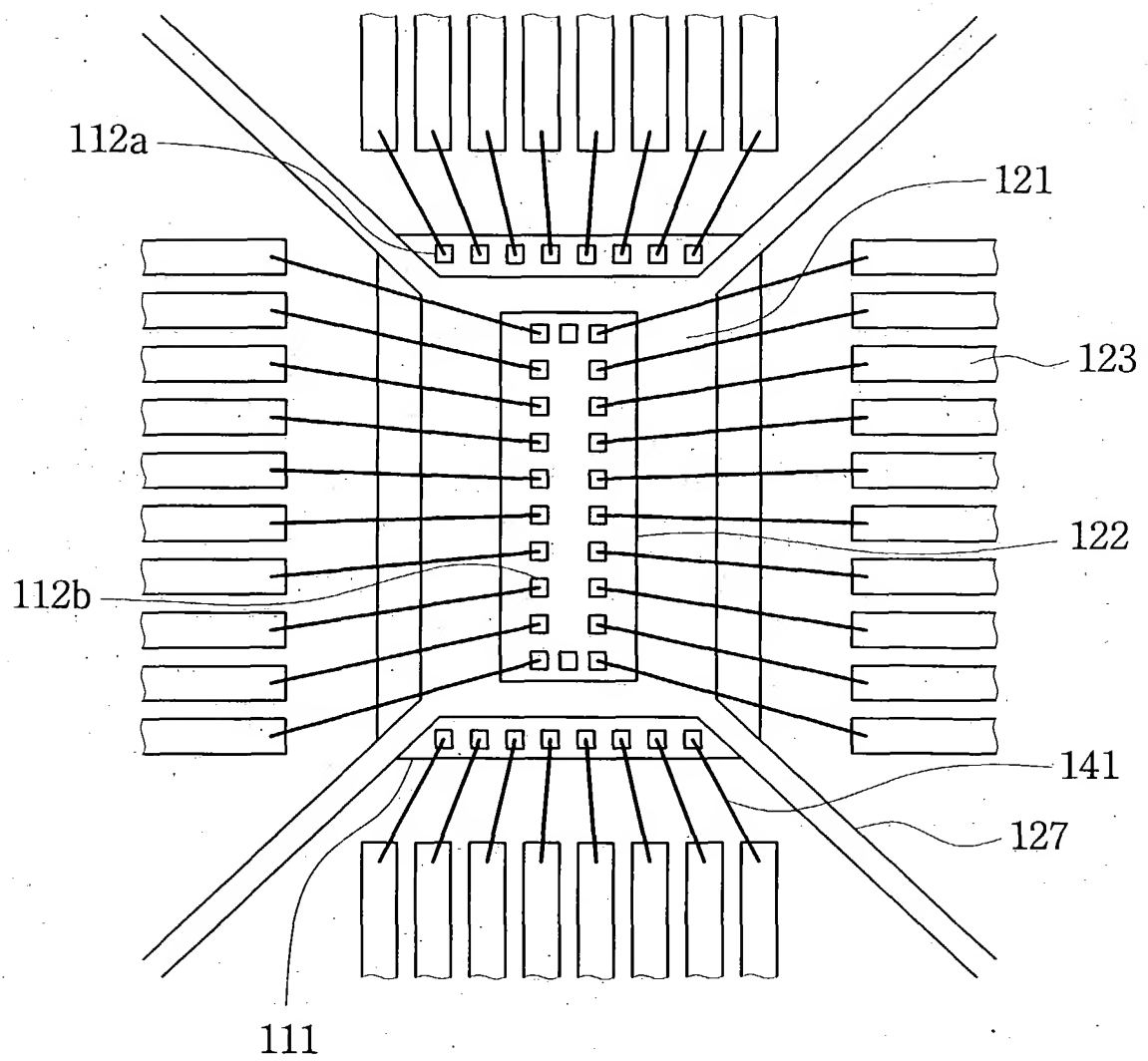


FIG. 11

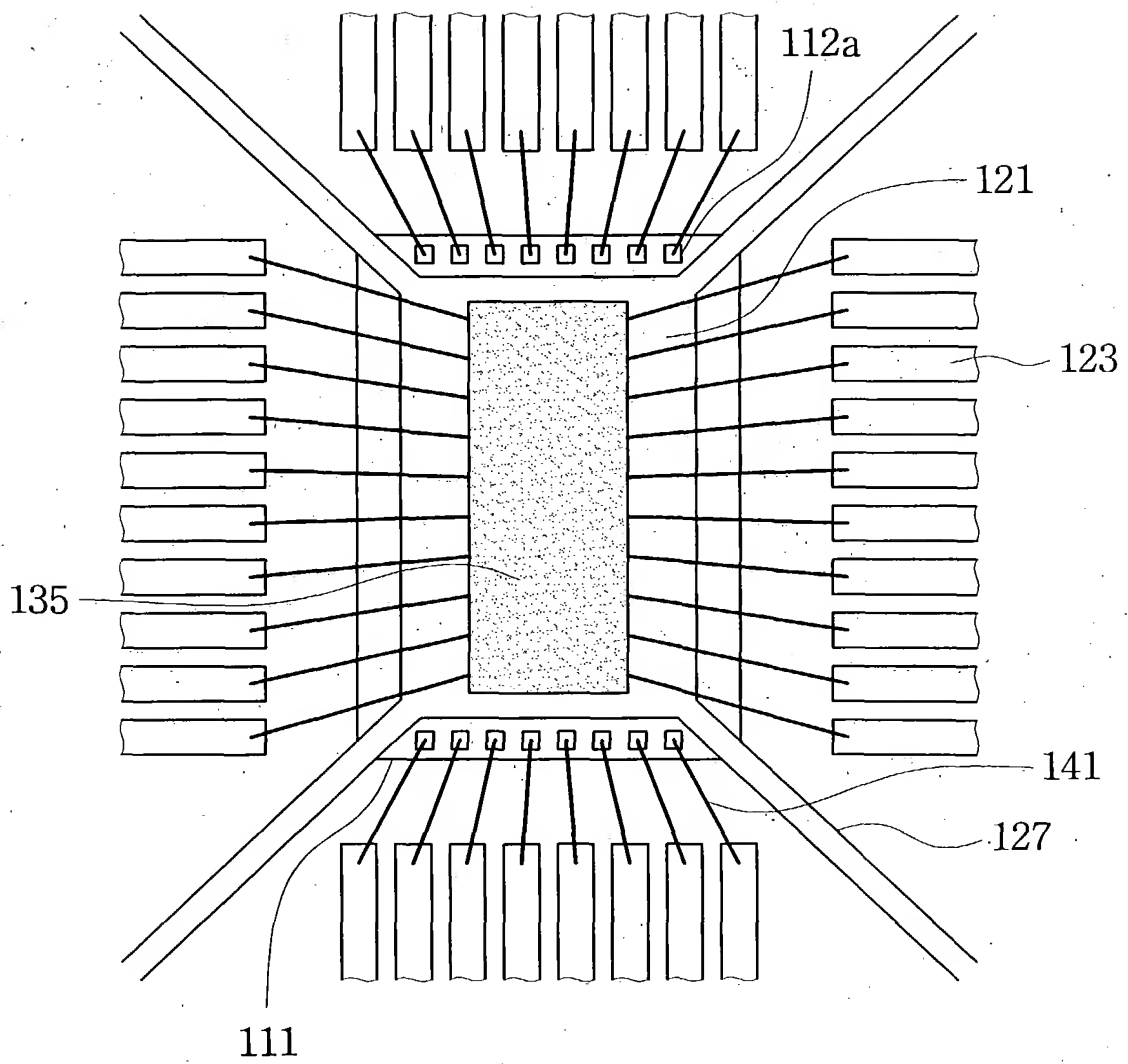


FIG. 12

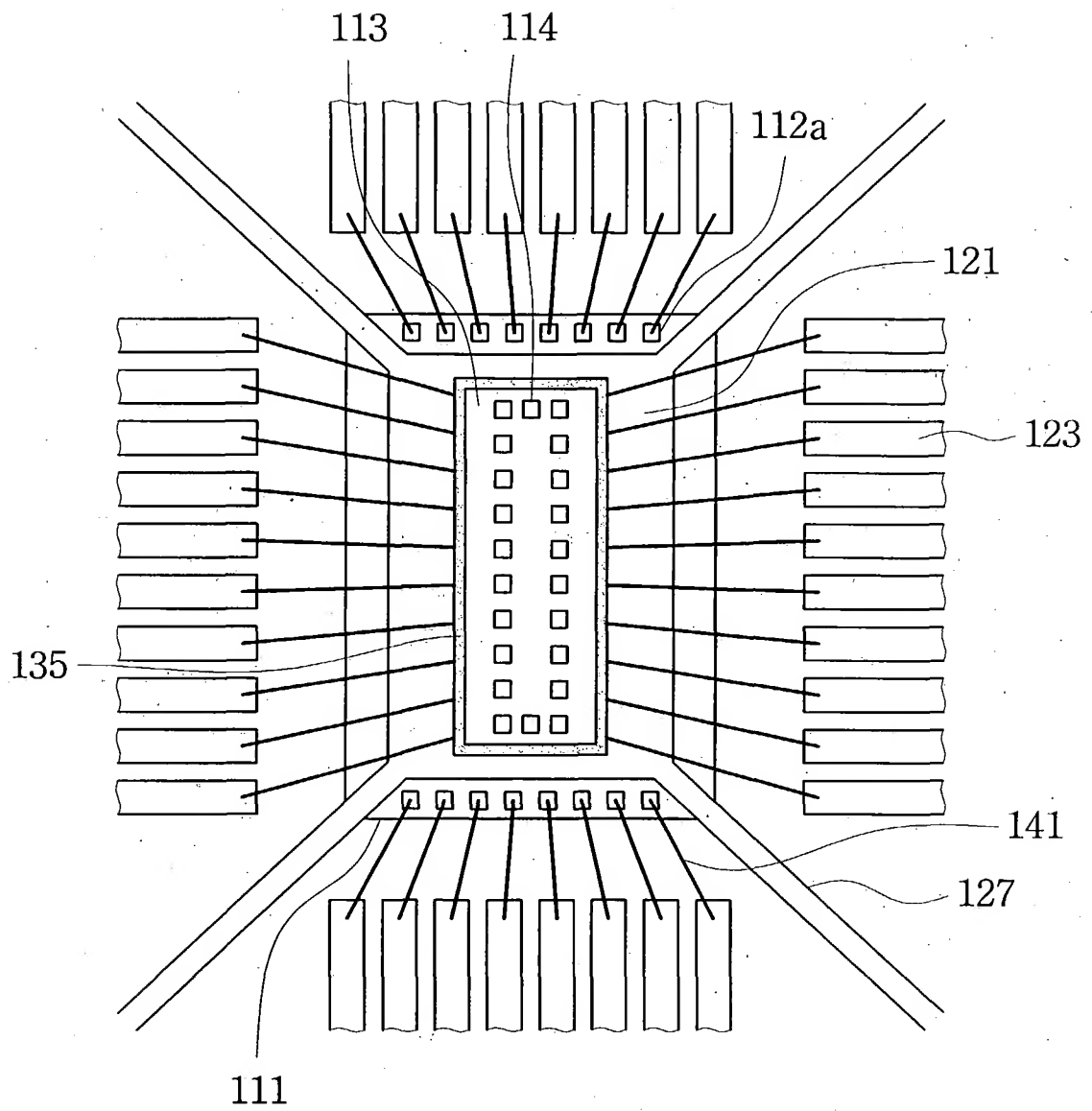


FIG. 13

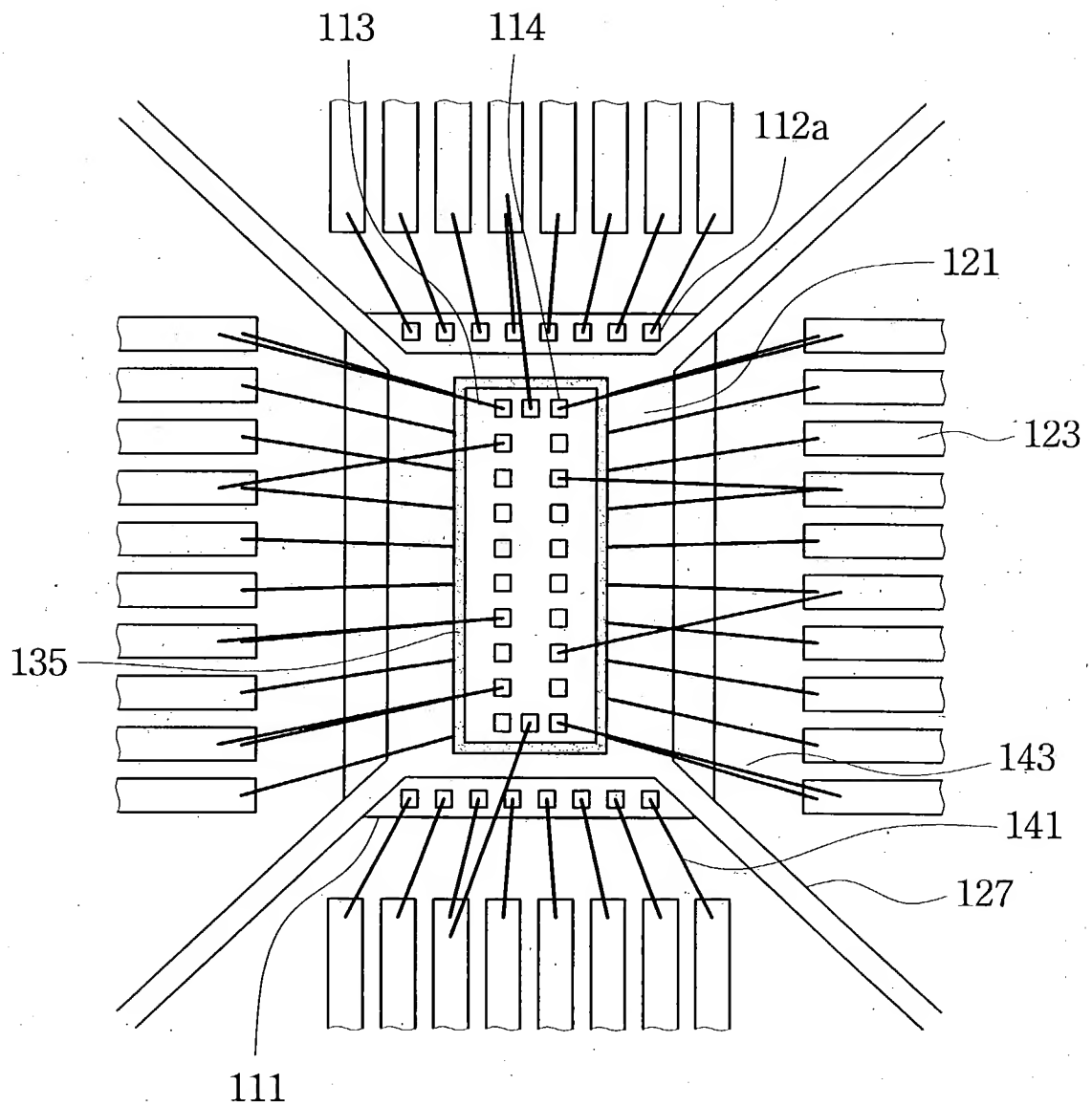


FIG. 14

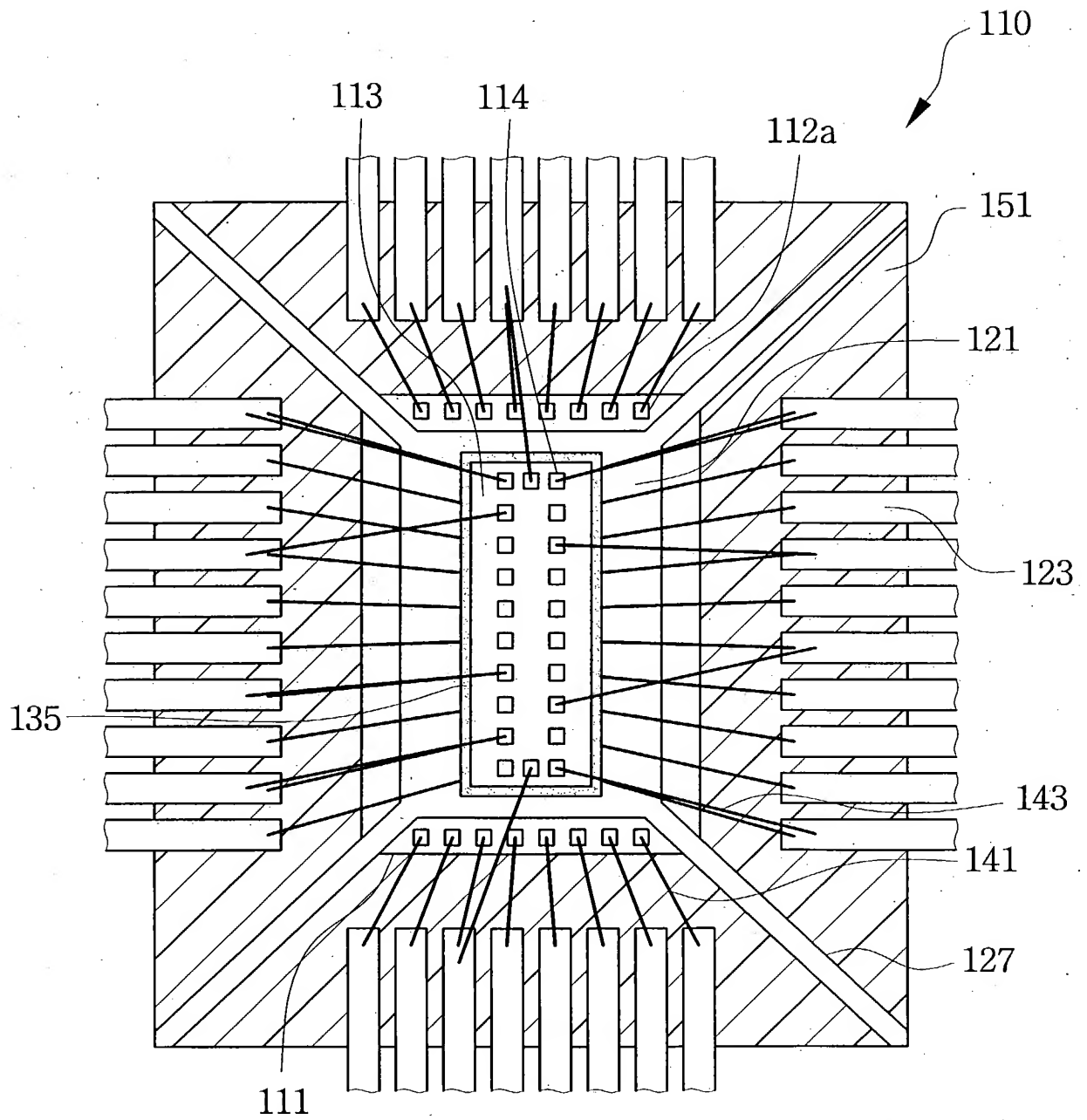


FIG. 15

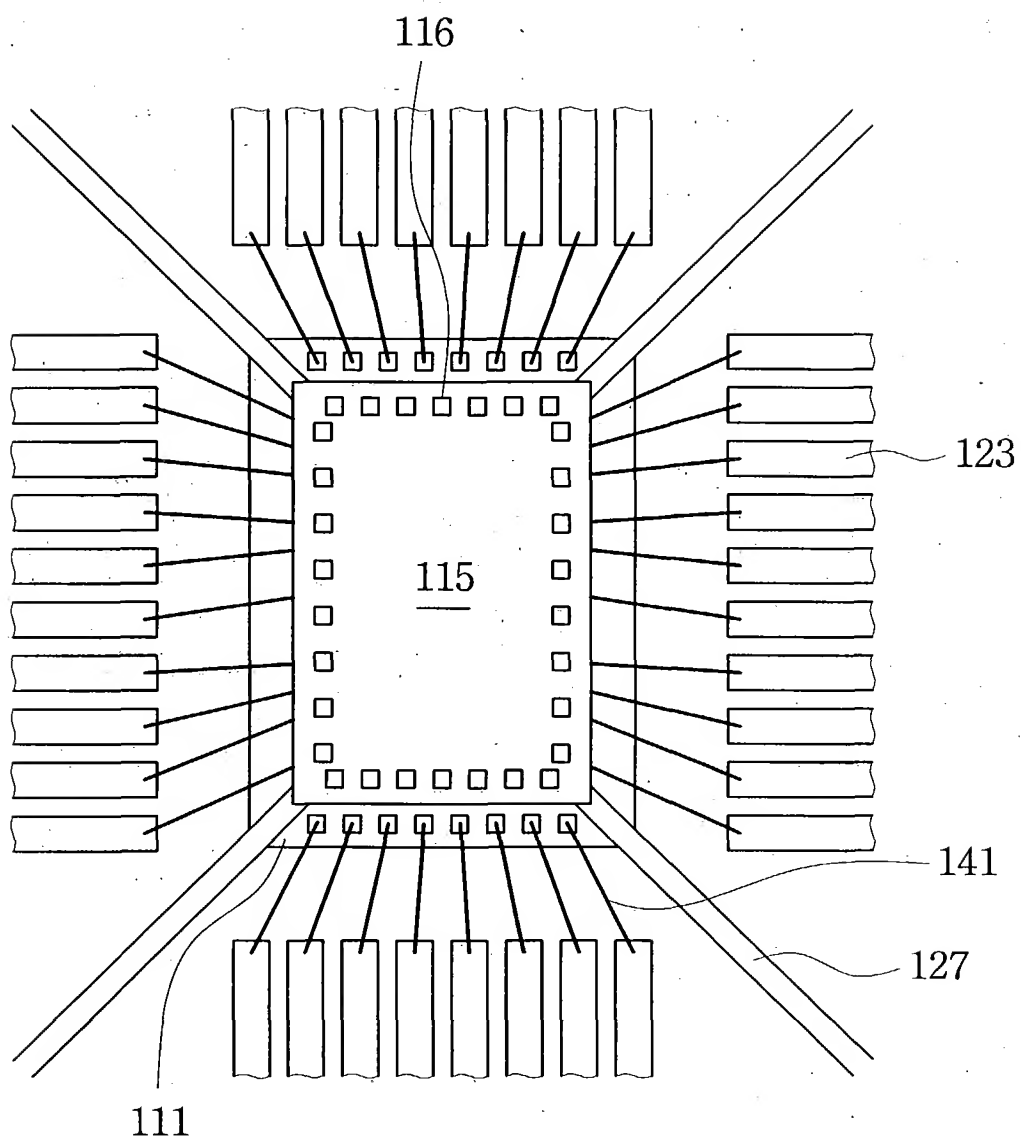


FIG. 16

